#### LBI-38975



# MAINTENANCE MANUAL RADIO FRONT ASSEMBLY 19D902177G17 CONVENTIONAL 19D902177G18 CONVENTIONAL/DTMF

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#### **DESCRIPTION**

The Radio Front Assembly (19D902177G17) for the PCS Portable Synthesized radio consists of the following components:

- Front Cap Assembly 19D902180G10
- Audio/Logic Board 19D902631G2
- Metal Over Elastomer (MOE) Connector 19A705662P1 and Holder 19B801570P2

The Radio Front Assembly (19D902177G18) for the PCS SCAN/DTMF Portable Synthesized radio consists of the following components:

- Front Cap Assembly 19D902180G11
- Audio/Logic Board 19D902631G2
- Metal Over Elastomer (MOE) Connector 19A705662P1 and Holder 19B801570P2

The front cap assembly consists of a LEXAN front housing, a control assembly, and a speaker.

The control assembly houses most operator switches/buttons, the Liquid Crystal Display (LCD), and the microphone. The Metal Over Elastomer (MOE) connector provides the interface between the printed runs on the control assembly and the printed runs on the Audio/Logic board.

The front housing contains the SCAN board (G17)or the SCAN/DTMF board that mounts the DTMF Pad (G18).

#### - NOTE -

All references to the SCAN function, equipment, and accessories apply only to the 8- and 16-channel radios.

#### FRONT CAP ASSEMBLY

Front cap assembly 19D902180G10 consists of a molded plastic circuit board (control frame), a Liquid Crystal Display (LCD) assembly, switches/buttons for the basic radio functions, and a Universal (User) Device Connector (UDC) all mounted in a plastic front housing.

Front cap assembly 19D902180G11 consists of a molded plastic circuit board (control frame), a Liquid Crystal Display (LCD) assembly, switches/buttons for the basic radio functions, and a Universal (User) Device Connector (UDC), all mounted in a plastic front housing. A DTMF keypad board is also mounted to the front housing. A SCAN/DTMF cable assembly connects this board to the Audio/Logic board.

The assembly diagram shows both a pictorial view of the control assembly and a view of the control assembly mounted into the radio front housing. The control frame acts like a three-dimensional printed circuit board.

The base material consists of "ULTEM" molded plastic with a two-layer printed circuit pattern on the outside perimeter of the frame. The control frame interfaces with the following:

- Control Switches/Buttons
- Liquid Crystal Display Module (LCD)
- Microphone
- Speaker
- User (Universal) Device Connector (UDC)

#### AUDIO/LOGIC BOARD

Audio/Logic board 19D902631G2 mounts in the Front Cap Assembly as shown in Figure 1. All Front Cap control switch operations are connected to the Audio/Logic board through MOE interface connector. The SCAN push-button board is connected by a cable to J802 on the Audio/Logic board.

A microprocessor on the Audio/Logic board interprets these commands and issues commands to the Audio/Logic circuits, the RF circuits and the LCD module on the control assembly. Microphone and speaker audio is also transferred through the MOE connector.

Refer to Figure 2 for a block diagram of the microprocessor and associated circuitry and to Figure 3 for a block diagram of the audio paths (see Table of Contents).

The Audio/Logic board consists primarily of the following:

- Microprocessor
- EEPROM
- RX Audio Processing
- TX Audio Processing
- Regulators and Special Circuits

#### **CIRCUIT ANALYSIS**

#### FRONT CAP ASSEMBLY

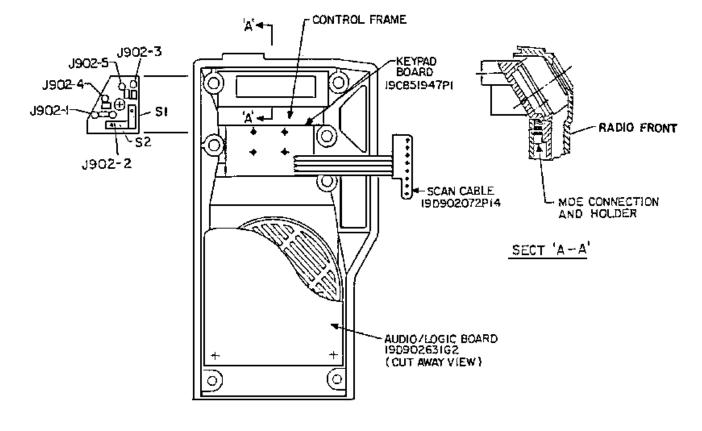
#### **Control Switches/Buttons**

The control switches/buttons include the PTT, MONitor, CHANnel UP/DOWN, and VOLume UP/DOWN controls. A "dome" switch pad adheres to the control frame with domed metal switches. When pressed, these switches make direct contact with runs on the control frame. A rubber keypad fits over the switch assembly for operator interface and weather protection.

#### **SCAN Switches**

The SCAN push-button switches consist of the ADD/HOME/EMERGENCY/BACKLIGHT, SCAN, and DE-Lete buttons, mounted on a small printed wiring board. Pressing these switches makes contact with the runs on the board. These lines are connected to the Audio/Logic board by a cable that plugs into the Audio/Logic board.

On the Radio Front Assembly (19D902177G18) the SCAN/TALK AROUND and DELete/POWER SET buttons are part of the DTMF keypad.



#### REAR VIEW

Figure 1 - Radio Front Assembly

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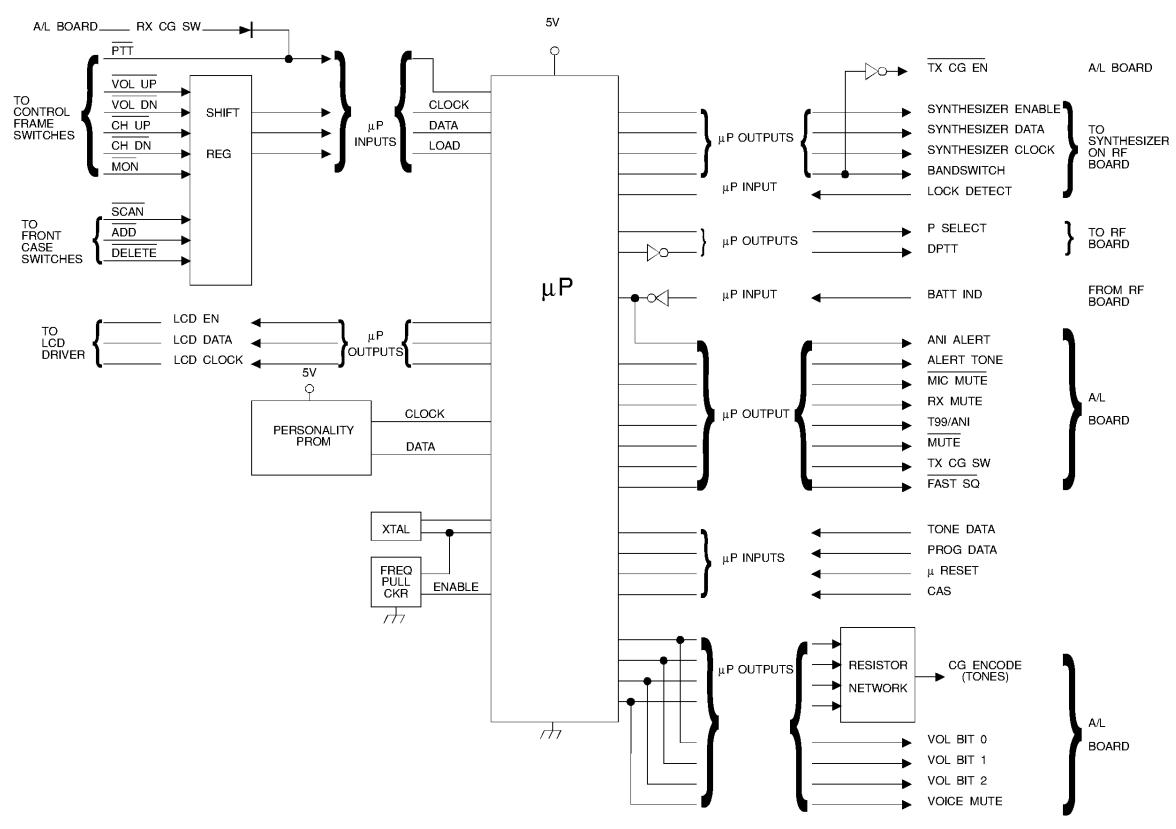


Figure 2 - Microprocessor Block Diagram

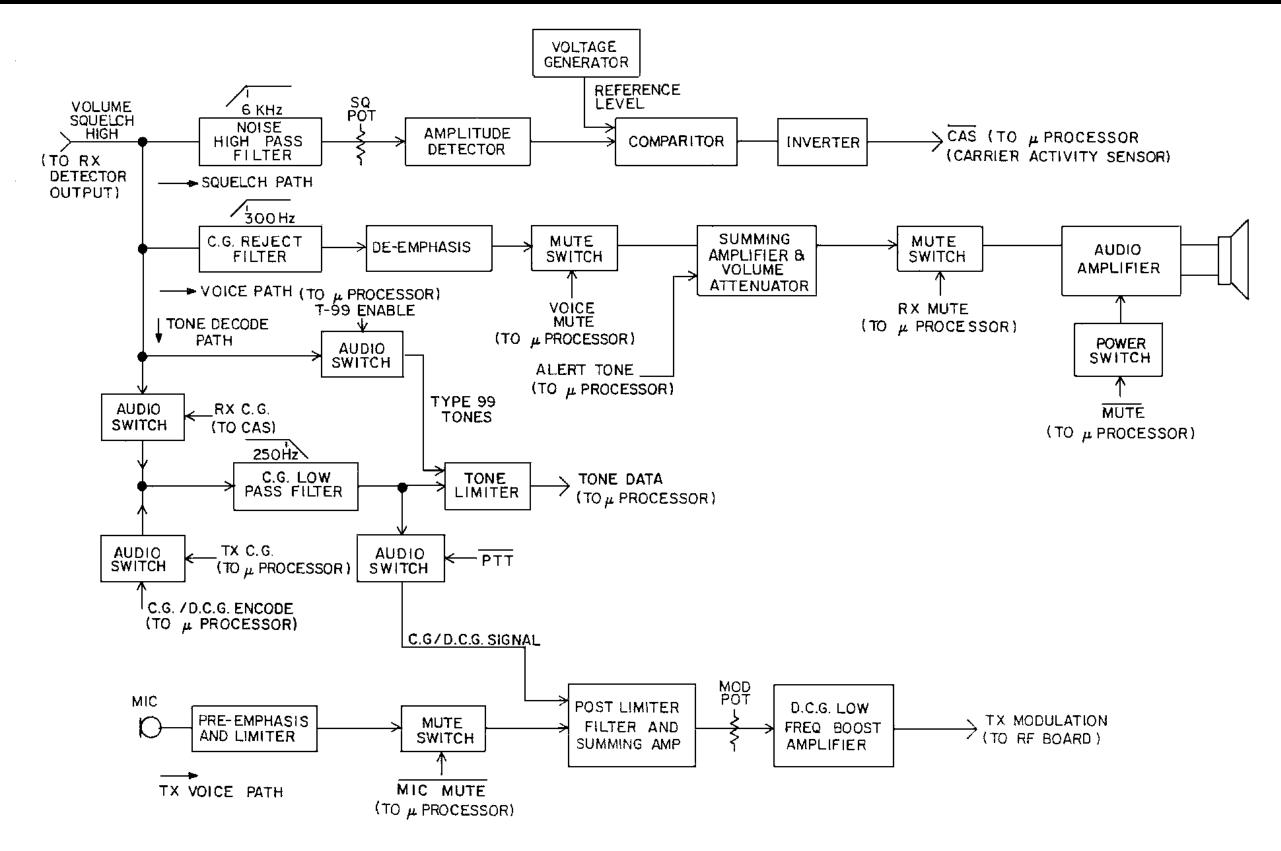


Figure 3 - Audio Paths Block Diagram

#### **DTMF Encoder**

The DTMF Encoder is used for encoding PCS personal radios with standard DTMF tones. The encoder consists of two parts: printed circuit board A1 and a twelve-key rubber keypad. The printed circuit board is mounted in the front cap assembly.

- The encoder performs the following functions:
- Generation of DTMF tone frequencies corresponding to digits dialed on the keypad.
- Continuous tone output as long as any digit is keyed on the keypad.
- Sidetone output to the radio speaker to permit monitoring the tones as they are transmitted.
- Uses standard tone format for high signalling reliability and equipment compatibility.

The DTMF Encoder uses standard dual tone multi-frequency format for telephone dialing. Each digit is identified by a unique combination of two tones; one corresponding to the horizontal row, and the other to the vertical column of push-button positions shown in Figure 4.

The frequencies are grouped about geometric center of the 300 to 3000 Hz voice band used in telephone and radio systems. The two tones are generated simultaneously and remain on as long as a digit on the keypad is being pressed. Row tones are in a lower frequency group than column tones. The frequencies are non-harmonic to give high immunity to false identification from beat frequencies and distortion-produced overtones.

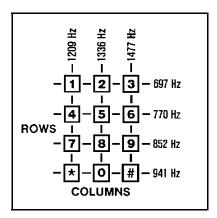


Figure 4 - Touch-Tone Keypad Frequency Format

#### **SCAN/DTMF Board**

The DTMF keypad is disabled until the PTT switch on the side of the radio is pressed and held. The PTT signal keys the microcomputer in the Audio/Logic board, Power and clock are toggled through J802.1 to the SCAN/DTMF microprocessor, enabling the oscillator. As the keypad buttons are pressed, digital signals, representing DTMF tones, are generated by ladder network resistors R8-R13. These

signals pass through the R-C filter (R14-R16 and C3-C5). Side tones are connected to the receive audio section through J802.8 and are then sent to the transmitter modulator through J801.5 (on Audio/Logic board).

#### **Liquid Crystal Display**

(LCD) consists of LCD driver board A1, a diffuser, two zebra strips, the LCD, and a lens. The LCD assembly is held together by the lens. The primary function of this board is to illuminate LCD segments as controlled by the radio microprocessor on the Audio/Logic board.

Another function of this board is to provide backlighting of the LCD module. This is accomplished by using four LED devices (D1-D4). These LED's are turned on by LCD DAT/LT line and powered by a voltage switching circuit consisting of chip transistors Q1 and Q2. The diffuser, placed immediately above the LED's, evenly distributes the light. The zebra strips connect the driver board to the LCD and the entire assembly plugs into the control frame with six pins.

#### **Microphone and Speaker**

The microphone (B901) mounts directly onto the control frame (HL1 and HL2). The control assembly, when placed into the radio front assembly, is located in the correct position for receiving voice when used. The speaker, mounted i the front housing, connects to the control frame (HL3 and HL4) through two (2) wires. A protective grill cloth is placed on the front housing before the speaker is mounted to screen out foreign material.

#### **User (Universal) Device Connector (UDC)**

Part of the control frame forms UDC U901 for customer programming and for connecting external options. The speaker leads, mic high, and PTT are all brought to this connector along with ground. The mic lead and one of the speaker leads are switched to the UDC, only when micro switches S1 and S2 are operated. These switches are activated by plungers compatible PCS personal radio options. A rubber boot is placed over this connector for weather protection.

#### AUDIO/LOGIC BOARD

#### Microprocessor (80C52)

An 8-bit microprocessor (U1) is used to provide all of the control signals required by the radio. The microprocessor also generates Channel Guard tones, Digital Channel Guard words, GE STAR, ANI words, and detects Channel Guard and Type 99 tones. The microprocessor is located on Spur Filter board (A701). The Spur Filter board includes RC filters on each port of the processor and a metal can soldered on top of the board to reduce the effect of the microprocessor-generated spurious signals.

**Table 1 - Microprocessor Port Pin Identification** 

Channel Guard Encode Bit 0/Volume Attenuator Bit 0	P2.0 (O)	LCD Enable
Channel Guard Encode Bit 1/Volume Attenuator Bit 1	P2.1 (O)	LCD Data
Channel Guard Encode Bit 2/Volume Attenuator Bit 2	P2.2 (O)	LCD Clock
Channel Guard Encode Bit 3/Volume Attenuator Bit 3	P2.3 (O)	Receive Mute (active high)
Low Battery Indication (active low)/ANI Alert	P2.4 (O)	T99/ANI
Transmit Channel Guard Switch (active high)	P2.5 (O)	Synthesizer Clock
Mute (active low)	P2.6 (O)	Synthesizer Data
Delayed PTT (active low)	P2.7 (O)	Synthesizer Data
Fast SQ	RXD (I)	Programmer Data
Load (serial load)	TXD (I/O)	Programmer Data Out/PTT
Clock (serial load)	P3.2 (I)	Tone Data
CAS (active low)	P3.3 (I)	Lock Detect
QH (active low) (serial load)	P3.4 (O)	Alert Tone
XTAL Bit	P3.5 (O)	Band Switch
Mic Mute (active low)	P3.6 (O)	E <sup>2</sup> PROM Clock
Power Select	P3.7 (O)	E <sup>2</sup> PROM Data
	O/Volume Attenuator Bit 0  Channel Guard Encode Bit 1/Volume Attenuator Bit 1  Channel Guard Encode Bit 2/Volume Attenuator Bit 2  Channel Guard Encode Bit 3/Volume Attenuator Bit 3  Low Battery Indication (active low)/ANI Alert  Transmit Channel Guard Switch (active high)  Mute (active low)  Delayed PTT (active low)  Fast SQ  Load (serial load)  CAS (active low)  QH (active low) (serial load)  XTAL Bit  Mic Mute (active low)	O/Volume Attenuator Bit 0  Channel Guard Encode Bit 1/Volume Attenuator Bit 1  Channel Guard Encode Bit 2/Volume Attenuator Bit 2  Channel Guard Encode Bit 3/Volume Attenuator Bit 3  Channel Guard Encode Bit 3/Volume Attenuator Bit 3  Low Battery Indication (active low)/ANI Alert  Transmit Channel Guard Switch (active high)  Mute (active low)  P2.5 (O)  P2.6 (O)  Delayed PTT (active low)  P2.7 (O)  Fast SQ  RXD (I)  Load (serial load)  TXD (I/O)  Clock (serial load)  P3.2 (I)  CAS (active low)  P3.3 (I)  QH (active low) (serial load)  XTAL Bit  P3.5 (O)  Mic Mute (active low)  P3.6 (O)

Port Pins I=Input O=Output I/O=Bidrectional

#### **EEPROM**

The 512 x 8-bit EEPROM (U701), commonly referred to as the personality PROM, stores customer information, such as:

- Customer frequencies
- Customer tones
- Customer options

Using the EEPROM provides the convenience of programming without opening the radio.

Programming of the EEPROM is accomplished by driving the MIC HI lead, which is connected to operational amplifier circuit U302.2. With no external signal connected to MIC HI, a voltage level of 2.1 volts is at MIC HI. This causes the output of U302.2 (the program data line) to be high.

When the MIC HI is pulled low, the program data line is pulled low. If this line remains low for 20 milliseconds or longer, the microprocessor is switched into the programming mode. Once in this mode, the radio will not operate or respond to any front case button. The radio must be turned off and then back on to get the processor out of this mode.

When the microprocessor is programmed, the processor will be taken out of the programming mode by the proper character from the personal computer programmer.

#### **RX Audio Processing**

#### **Voice Path**

Received audio enters the Audio/Logic board on Pin 10 of J801. Frequencies below 300 Hz are attenuated by the Channel Guard reject filter consisting of U602.1 and associated circuitry.

The output from the CG reject filter is coupled through voice mute switch transistor Q603 to the volume attenuator circuit U602.2, and resistors R632 through R640. The feedback resistors are selected by bilateral switch Q603 and controlled by inputs volume bit 0, 1, and 2. Here the 500 Hz alert tone, generated by the microprocessor, can be added to the received audio at the alert tone input.

The volume attenuator has a range of 48 dB. The attenuator output is coupled through RX MUTE switching transistor Q606 to audio amplifier transistor U604. ANI alert is coupled to U604 input through C608 and R673. Power is supplied to the audio amplifier by transistors Q605 and Q606 and controlled by the MUTE line from the microprocessor. Amplifier U604 drives the speaker with differential outputs, which are also connected to the accessory connector through the control assembly.

A 6 dB/octave de-emphasis is provided by capacitor C615 and resistor R628 in the CG reject filter. Capacitor C622 and resistor R644 provide additional roll-off at higher frequencies.

#### **Squelch Path**

The squelch circuit operates on the noise components contained in the discriminator output. The signal at J801-10 is applied to a high-pass filter consisting of U601.2 and associated circuitry. The output of U601.2 is noise in a band around 6 kHz. The gain of the high-pass filter is determined by squelch potentiometer R608.

The output of U601.2 is rectified by U601.1, resistors R610 through R612, and capacitors C607 and C639. C607 is switched into operation by Q609. The Fast Squelch line, in turn, controls Q609. C607 is always switched into operation during a non-SCAN operation. During SCAN operation, C607 is switched out of the circuit for rapid squelch operation. This DC signal is then applied to comparator U601.4. If the rectified noise is more than 0.20 VDC, the CAS line is high and the microprocessor mutes the audio. Feedback resistor at U601.4 provides about 2 dB of hysteresis. Resistors R614, R662, R663, and thermistor R664 are used for temperature compensation or the threshold level.

The threshold level is temperature compensated at cold temperatures only by thermistor R664. This is necessary because of a drop in the VOL/SQ HI noise level. Thermistor R664 has a negative temperature coefficient. At 25° C and above, the thermistor has little effect on the threshold voltage level at U601B, Pin 12. At temperatures below 25° C, the resistance increases exponentially, thereby causing a drop in the threshold voltage. This voltage drop approximately tracks the voltage drop at the detected noise terminal, U601.2-13.

#### **Limited Tone Data Path**

Limited Tone Data is the 5 volts (peak-to-peak) representation of a received tone and is fed to the microprocessor where the actual tone decoding occurs. This circuit consists of an amplifier followed by a low-pass filter for voice rejection and a voltage comparator.

The low-pass filter consists of U606.1 and associated circuitry. This filter is used for both Channel Guard encoding and decoding. The filter has a breakpoint at 210 Hz. Type 99 decoding is done by bypassing the low-pass filter and going directly to comparator U606.2.

#### **TX Audio Processing**

Audio from the microphone is applied to a 6 dB/octave pre-emphasis network consisting of capacitor C301 and resistor R306 and then to amplifier U301.1. Amplifier U301.2 provides further gain and symmetrical limiting. The output of U301.2 is coupled through mic mute switch U605.3 to the post-limiter filter consisting of U302.1 and associated circuitry. Transmit Channel Guard tones are added to the microphone audio at the post-limiter filter. GE STAR ANI is also fed into post-limiter filter when programmed.

The transmit signal is applied to the low-frequency boost circuit U303.1, U303.2, and associated circuitry. The transmit deviation is set by MOD potentiometer R3211.

The low-frequency boost circuit provides an increasing output level as the input frequency decreases below 20 Hz. The shape of the response curve is shown in Figure 5. This shape is intended to be the mirror image of the synthesizer frequency response curve. The combined result of these two curves provide relatively flat modulation below 5 Hz. This is necessary for Digital Channel Guard modulation.

#### **Regulator and Special Circuitry**

 $A+5\,volt\,regulator\,U802\,supplies$  power to the microprocessor and all other circuitry requiring +5 volts. A voltage divider provides the input to U601.3 to generate a 2,25 volt reference for operational amplifier biasing.

#### **Low Voltage Reset**

Voltage detector U801 and transistor Q803 provide the microprocessor with the necessary reset signal during the power-up routine as well as resetting the microprocessor when the battery falls below approximately 4.75 volts (see Figure 6).

#### **Low Battery Indicator**

When the battery voltage drops to approximately 6.3 volts, the BAT IND line from the RF board is sufficiently high to turn on Transistor Q802. The output of Q802, the low battery line, drives a microprocessor port. This action turns on the BAT pixel on the LCD.

#### **User Input**

Control assembly connector J901 and SCAN connector J802 on the Audio/Logic board provide the interface between the operator and the radio. By pressing buttons on the switch panel or SCAN keypad, the operator can:

- Change volume level or channel.
- Monitor a channel.
- Key the transmitter.
- Turn SCAN on or off.
- Add or delete SCAN channels from the Scan list.
- Switch to HOME channel.

All operator commands are applied to an 8-bit shift register U803, which loads the data and control inputs into the microprocessor through J701-3, J701-4, and J701-6.

The LCD is updated to reflect the current status of the radio. The microprocessor configures the LCD through LCD EN (P2.0), LCD DAT (P2.1), and LCD CLK (P2.2).

#### **Synthesizer Programming**

After a reset, when toggling between transmit and receive, and anytime a new channel is selected, the microprocessor must reprogram the synthesizer through SYN CLK (P2.5), SYN DAT (P2.7), and SYN EN (P2.6). When locked, the LOCK DET line (J9801-11) is high.

#### **Alert Tone**

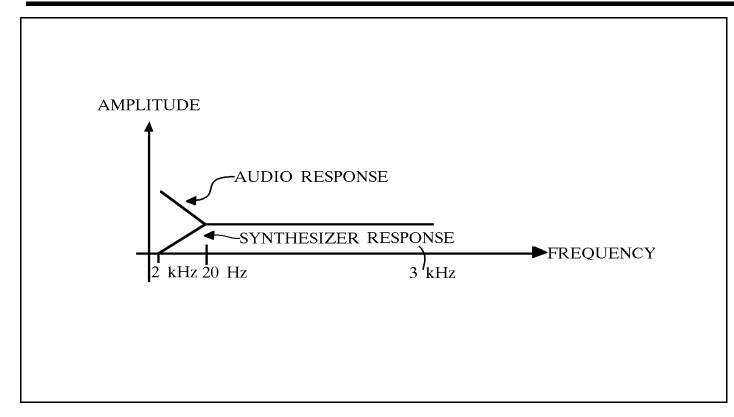
The microprocessor generates a 500 Hz alert tone (P3.4) used to signal the user of critical events. These events include synthesizer out-of-lock and activation of the volume up, volume down, and channel up buttons. The alert tone can be disabled by the programmer.

#### **Microprocessor XTAL Frequency Pull**

Port P1.5 of the microprocessor is used to switch a 33 pF capacitor (C701) into the crystal oscillator circuit. The effect of adding this capacitor is to move or pull the XTAL frequency approximately 250 ppm. This is done to keep harmonics of the microprocessor ALE line away from the receive channel frequency.

The programming at this point happens automatically when channel frequencies are initially programmed.

#### LBI-38975



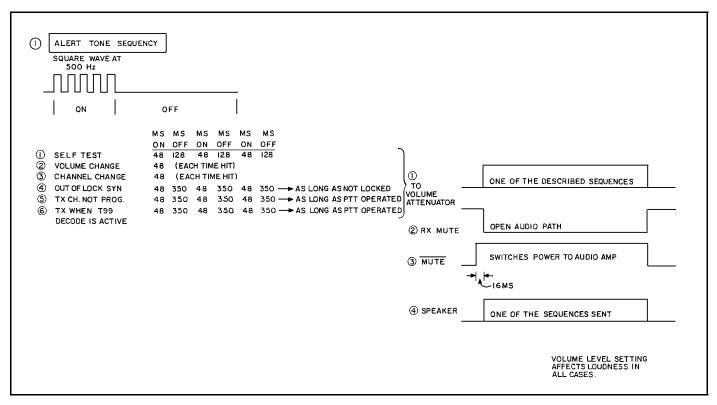


Figure 5 - Audio Response Curve

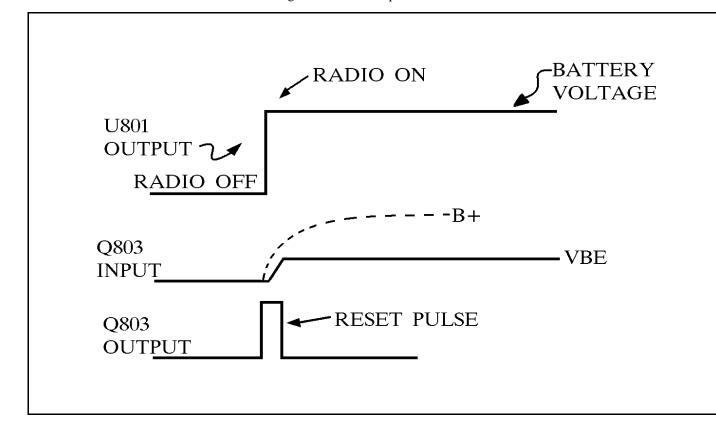


Figure 7 - Alert Tones

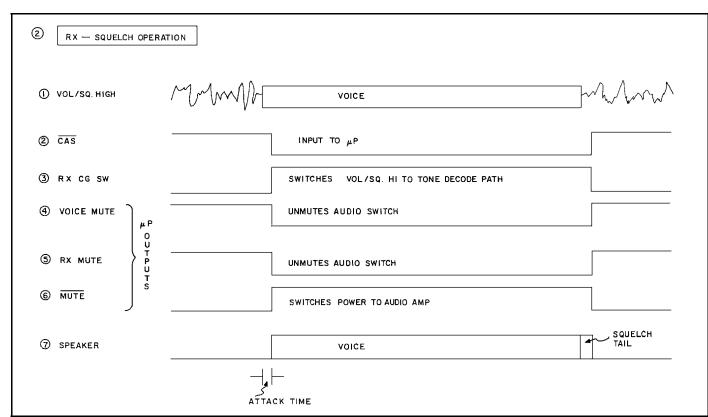


Figure 6 - Voltage Waveforms

Figure 8 - RX Squelch Operation

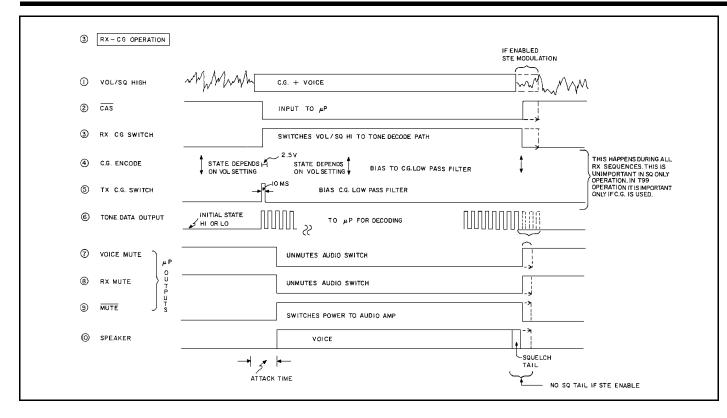


Figure 9 - RX Channel Guard Operation

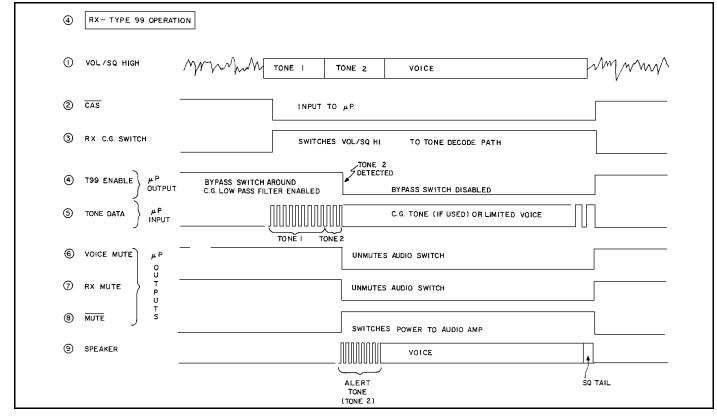


Figure 10 - RX Type 99 Operation

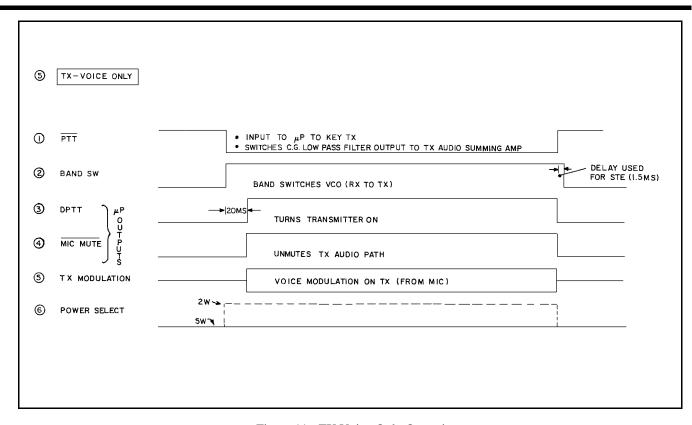


Figure 11 - TX Voice-Only Operation

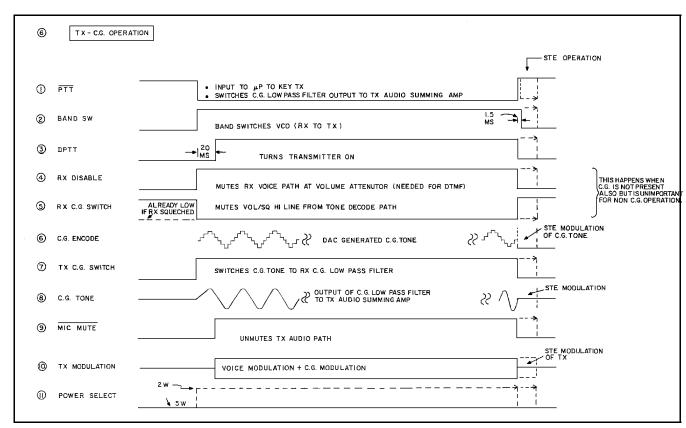
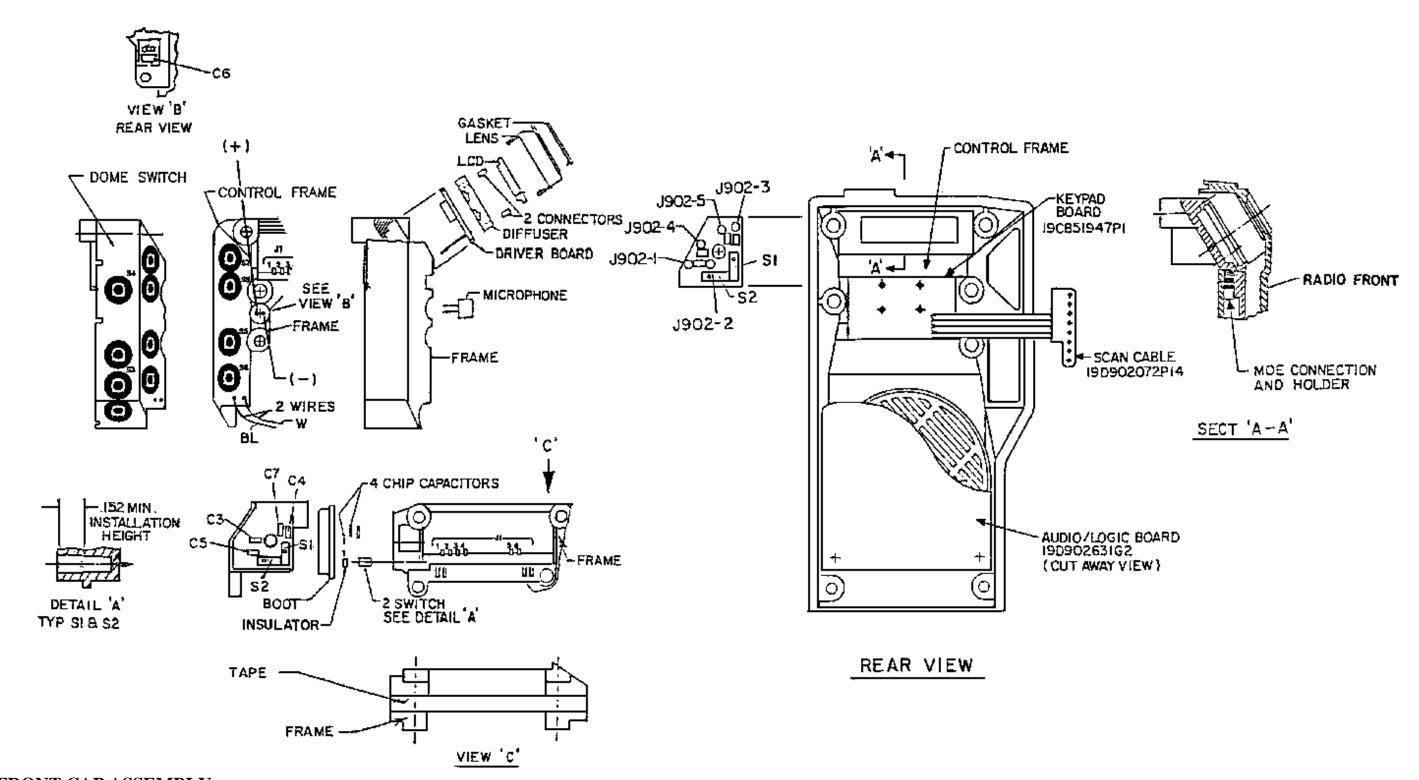


Figure 12 - TX Channel Guard Operation

LBI-38975 ASSEMBLY DIAGRAM



#### FRONT CAP ASSEMBLY

19D902180G10 & G11

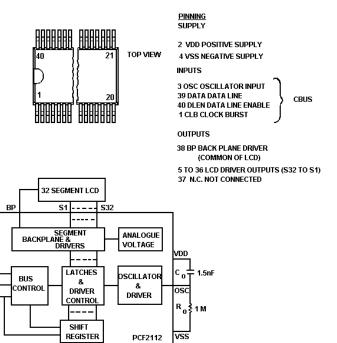
(19D902180, SH. 1, REV. )

I C DATA LBI-38975

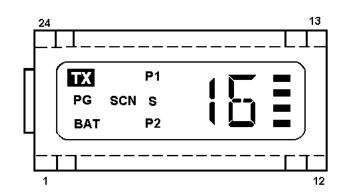
#### LCD DRIVER U1

CLB ·

19A705714P1



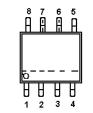
#### LCD 19C851660P2

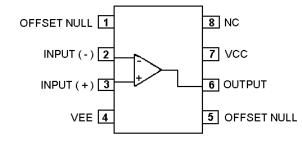


	PIN OUT				
1	COM		13	NC	
2	PG		14	BAR 2	
3	BAT		15	BAR 3	
4	SCN		16	BAR 4	
5	P2		17	1B	
6	ONE		18	1A	
7	1E		19	1F	
8	1D		20	1G	
9	1C		21	P1	
10	BAR 1		22	S	
11	NC		23	TX	
12	COM		24	COM	

#### **OPERATIONAL AMPLIFIER U301**

19A705450P3

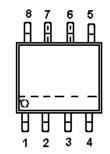


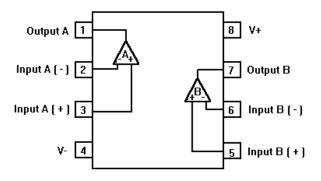


#### **OPERATIONAL AMPLIFIER**

U302/U602/U603

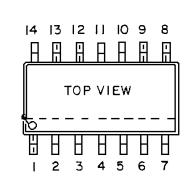
19A702293P2

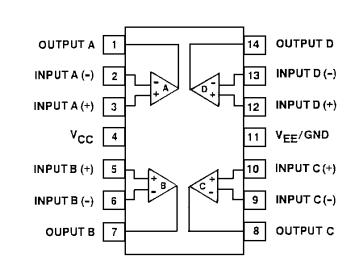




#### **OPERATIONAL AMPLIFIER U601**

19A702293P1

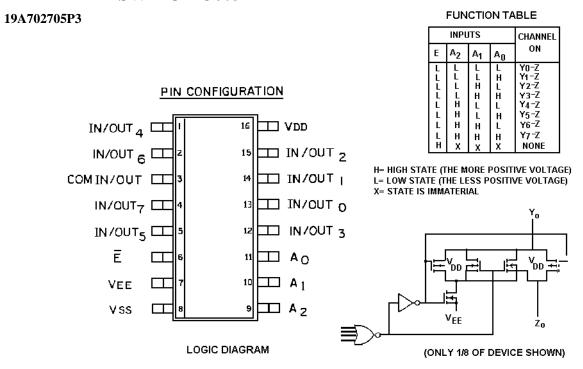




PIN I MAY BE IDENTIFIED BY INDENT OR CHAMFER

LBI-38975 I C DATA

#### **BILATERAL SWITCH U603**

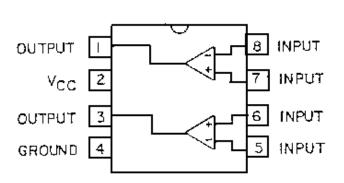


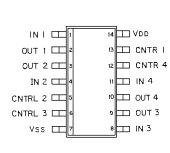
#### **AUDIO AMPLIFIER U604**

19A705452P1

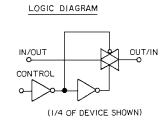
#### **BILATERAL SWITCH U605**

19A702705P1





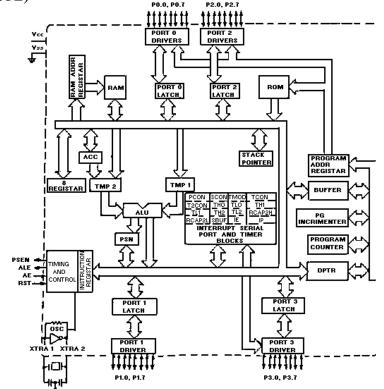
PIN CONFIGURATION



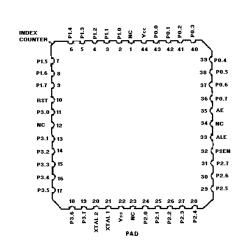
CONTROL	SWITCH
0	OFF
1	ON

#### **MICROPROCESSOR U1 (80C52)**

19A705557P4



FUNCTION DIAGRAM

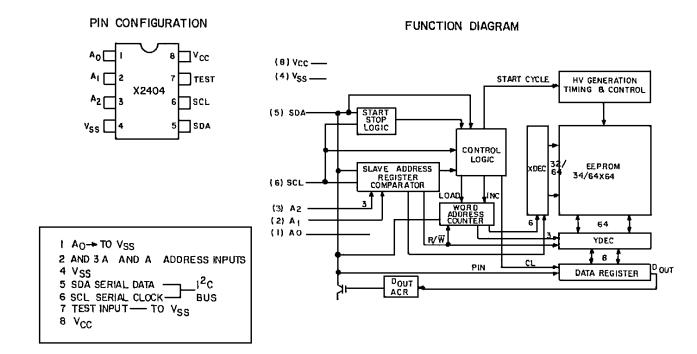


VSS	CIRCUIT GROUND POTENTIAL
VCC.	+SV POWER SUPPLY
PORT 0	8-BIT OC BI-DIRECTIONAL I/O PORT.
PORT 1	8-BIT QUASI-BIDIRECTIONAL I/O FORT.
PORT 2	8-BIT QUASI-BIDIRECTIONAL (/O FORT.
FORT 3	8-BIT QUASI-BIO/RECTIONAL I/8 FORT.
3.0	RXD — SERIAL PORT RECEIVER DATA.
2.1	TXD — SERIAL POST TRANSMITTER DATA
3.2	INTO - INTERRUPT O INPUT.
3.3	INT1 — INTERRUPT 1 INPUT.
3.5	T1 - COUNTER 1 HIPUT.
3.6	WR — WRITE CONTROL.
3.7	RD — READ CONTROL
AST	RESET.
ALE	ADDRESS LATCH ENABLE.
PSEN	PROGRAM STORE ENABLE OUTPUT.
EA	INTERNAL/EXTERNAL INSTRUCTION FETCH.
XTAL1	INPUT TO OSCILLATOR AMPLIFIER.
XTALZ	OUTPUT FROM OSCILLATOR AMPLIFIER.

I C DATA LBI-38975

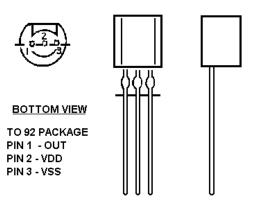
#### **EEPROM U701**

#### 19A704724P1



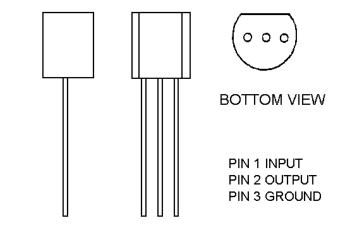
#### **VOLTAGE DETECTOR**

19A705454P1



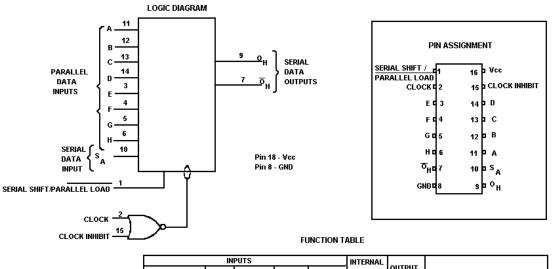
#### **VOLTAGE REGULATOR U802**

19A702536P1



#### **SHIFT REGISTER U803**

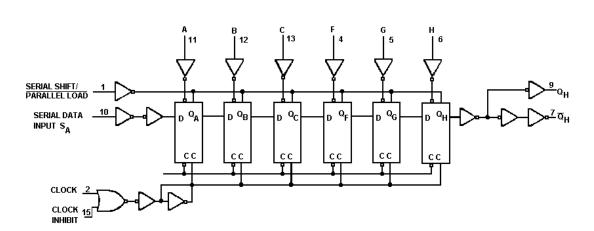
19A703987P322



	INPUTS				INTE	RNAL		
SERIAL SHIFT/ PARALLEL LOAD	СГОСК	CLOCK INHIBIT	SA	А Н	ST.	AGES Q <sub>B</sub>	оитрит <sup>Q</sup> н	OPERATION
L	x	X	X	ah	a	b	h	ASYNCHRONOUS PARALLEL LOAD
н н	\\		LH	x x	н	Q <sub>An</sub> Q <sub>An</sub>	Q <sub>Gn</sub>	SERIAL SHIFT VIA CLOCK
H H	L	ኣኣ	L H	x x	L H	Q <sub>An</sub> Q <sub>An</sub>	Q <sub>Gn</sub> Q <sub>Gn</sub>	SERIAL SHIFT VIA CLOCK INHIBIT
H H	Х	H X	×	x x		но сн	ANGE	INHIBITED CLOCK
Н	L	L	х	x		но сн	ANGE	NO CLOCK

X = DON'T CARE

#### EXPANDED LOGIC DIAGRAM

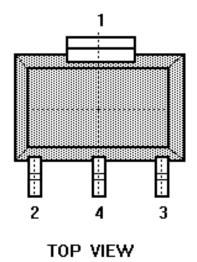


 $<sup>^{</sup>Q}$ An $^{-Q}$ Gn = DATA SHIFTED FROM PRECEDING STAGE

LBI-38975 IC DATA

#### 48-BIT SERIAL NUMBER ROM U804

344A4050P101



PIN NAMES

Pin 1 Ground

Pin 2 Data (DQ)

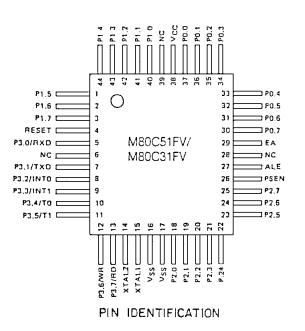
Pin 3 No Connect

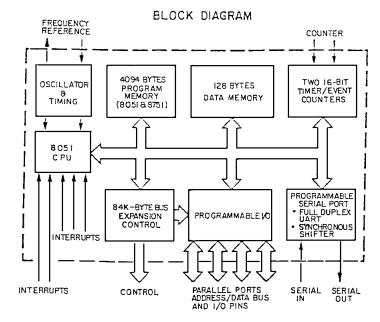
Pin 4 Ground

#### MICROPROCESSOR U1 (80C51)

19A704345P30

CHMOS 8-BIT MICROCOMPUTER 19 A704345P20,21,30





PARTS LIST LBI-38975

#### FRONT CAP ASSEMBLY (CONVENTIONAL) 19D902177G17

#### (CONVENTIONAL/DTMF) 19D902177G18

	19D902177G18				
SYMBOL	PART NO.	DESCRIPTION			
A2 A701	19D902631G2 19C851678G4	AUDIO/LOGIC BOARD SPUR FILTER BOARD			
C1		CAPACITORS			
thru C34	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30			
C35 C36	19A702052P14 19A702061P35	PPM/°C. Ceramic: 0.01 $\mu$ F ±10%, 50 VDCW. Ceramic: 30 pF ±5%, 50 VDCW, temp coef 0±30 PPM.			
P701	19B801573P1	Connector.			
R1	19B801251P102	RESISTORS Metal film: 1K ohms ±5%, 1/10 w.			
R2 and R3 R4	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.			
and R5 R6	19B801251P102 19B801251P101	Metal film: 1K ohms ±5%, 1/10 w. Metal film: 100 ohms ±5%, 1/10 w.			
R7 thru R14	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.			
R15 thru R17	19B801251P101	Metal film: 100 ohms ±5%, 1/10 w.			
R18 thru R22	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.			
R23 thru R25 R26	19B801251P471	Metal film: 470 ohms ±5%, 1/10 w.			
thru R30 R31	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.			
thru R34 R35	19B801251P101 19B801251P220	Metal film: 100 ohms ±5%, 1/10 w. Metal film: 22 ohms ±5%, 1/10 w.			
U1	RYTUA12301/C	INTEGRATED CIRCUITS Microcomputer: 8-bit, CHMOS; 8XC524.			
C301 C302 C303	19A702052P7 19A702052P30 19A702061P61	Ceramic: 2200 pF ±10%, 50 VDCW. Ceramic: 0.022 μF ±10%, 50 VDCW. Ceramic: 100 pF ±5%, 50 VDCW, temp coef 0±30 PPM.			
C304 C305 C306 C307 C308 C309	19A702052P26 19A702052P10 19A705205P2 19A702052P107 19A702052P30 19A702061P67	Ceramic: $0.1  \mu F \pm 10\%$ , 50 VDCW Ceramic: $4700  pF \pm 10\%$ , 50 VDCW. Tantalum: $1  \mu F$ , $16  VDCW$ ; sim to Sprague 293D. Ceramic: $2200  pF \pm 5\%$ , 50 VDCW. Ceramic: $0.022  \mu F \pm 10\%$ , 50 VDCW. Ceramic: $180  pF \pm 5\%$ , 50 VDCW, temp coef $0\pm 30  PPM$ .			
C310 C311 C312	19A702052P26 19A702052P30	Ceramic: $0.1  \mu\text{F} \pm 10\%$ , 50 VDCW Ceramic: $0.022  \mu\text{F} \pm 10\%$ , 50 VDCW.			
and C313 C314	19A702052P26 19A702061P73	Ceramic: 0.1 µF ±10%, 50 VDCW Ceramic: 330 pF ±5%, 50 VDCW, temp coef 0±30 PPM/°C.			
C315 and C316 C317 C318 C319	19A702052P26 19A702052P30 19A702052P26 19A702061P45	Ceramic: $0.1~\mu\text{F}~\pm10\%, 50~\text{VDCW}$ Ceramic: $0.022~\mu\text{F}~\pm10\%, 50~\text{VDCW}$ . Ceramic: $0.1~\mu\text{F}~\pm10\%, 50~\text{VDCW}$ Ceramic: $47~\text{pF}~\pm5\%, 50~\text{VDCW}$ , temp coef $0\pm30~\text{PPM}$ .			
C601 C602	19A702052P107 19A702061P77	Ceramic: 2200 pF ±5%, 50 VDCW. Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30 PPM.			
C603	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0 ±30 PPM.			
	l	1			

SYMBOL	PART NO.	DESCRIPTION
C604	19A702052P105	Coronia, 4000 pF LEW EQ VDCW
C605	19A702052P105	Ceramic: 1000 pF ±5%, 50 VDCW. Ceramic: 2200 pF ±10%, 50 VDCW.
C606	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW
C607	19A705205P2	Tantalum: 1 μF, 16 VDCW; sim to Sprague 293D.
C608	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30
C609	19A702052P30	PPM. Ceramic: 0.022 μF ±10%, 50 VDCW.
C610	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW.
C611		
and C612	19A702052P114	Coromics 0.04E JE9/ F0.VDCW
C613	19A702052F114	Ceramic: 0.01 μF ±5%, 50 VDCW. Ceramic: 0.022 μF ±10%, 50 VDCW.
C614	19A702052P26	Ceramic: 0.022 μ ±10%, 50 VDCW
C615	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW.
C616	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.
C617	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.
C618	19A702052P5	Ceramic: 1000 pF ±10%, 50 VDCW.
C619	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.
C620	19A704879P14	Electrolytic: 68 μF ±20%, 10 VDCW.
C621	19A702052P30 19A702052P30	Ceramic: 0.022 μF ±10%, 50 VDCW.
C622 C623	19A702032F30 19A704879P5	Ceramic: 0.022 μF ±10%, 50 VDCW.
C624	19A702052P14	Electrolytic: $10 \mu F \pm 20\%$ , $16 VDCW$ . Ceramic: $0.01 \mu F \pm 10\%$ , $50 VDCW$ .
C626		33.απιο. 3.61 μι ±10/0, 30 V DOVV.
and	40470	
C627	19A702052P26	Ceramic: 0.1 μF ±10%, 50 VDCW
C628 C629	19A705205P2	Tantalum: 1 μF, 16 VDCW; sim to Sprague 293D.
and		
C630	19A702052P10	Ceramic: 4700 pF ±10%, 50 VDCW.
C631	19A702052P14	Ceramic: 0.01 μF ±10%, 50 VDCW.
C632 C633	19A702052P22 19A702052P7	Ceramic: 0.047 μF ±10%, 50 VDCW.
C634	19A702052F7 19A143565P12	Ceramic: 2200 pF ±10%, 50 VDCW. Ceramic: 220000 pF ±10%. 50 VDCW; sim to KE
0034	19A143303F12	MET C323C224K5R5CA.
C635	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30
C636		PPM/°C.
thru		
C638	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30
C639	19A702052P26	PPM/°C.
C639 C640	19A702052F20 19A702052F10	Ceramic: 0.1 μF ±10%, 50 VDCW Ceramic: 4700 pF ±10%, 50 VDCW.
C641	19A702052P12	Ceramic: 4700 pr ±10%, 50 VDCW.
C642	19A702236P36	Ceramic: 27 pF ±5%, 50 VDCW, temp coef 0±30
		PPM/°C.
C643	19A702052P134 19A702061P37	Ceramic: 0.1 μF ±5%, 25 VDCW.
C701	19A702001F37	Ceramic: 33 pF ±5%, 50 VDCW, temp coef 0±30 PPM/°C.
C703	19A702061P77	Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30
C704	19A702061P77	PPM. Ceramic: 470 pF ±5%, 50 VDCW, temp coef 0±30
C705	19A702061P69	PPM. Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30
		PPM/°C.
C801	19A705205P2	Tantalum: 1 μF, 16 VDCW; sim to Sprague 293D.
C804 C805	19A702052P14 19A701534P9	Ceramic: 0.01 μF ±10%, 50 VDCW.
C805	19A701534P9 19A704879P5	Tantalum: 47 μF ±20%, 6.3 VDCW. Electrolytic: 10 μF ±20%, 16 VDCW.
C807	19A705205P14	Tantalum: 6.8 μF, 6 VDCW; sim to Sprague 293D.
C808	19A702061P69	Ceramic: 220 pF ±5%, 50 VDCW, temp coef 0±30
		PPM/°C.
		DIODES
D601	19A705377P3	Silicon, Hot Carrier: sim to HSMS-2920.
D701	194705577F5	Silicon, not Carrier. Silii to HSW3-2920.
thru		
D705 D707	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
and		
D708	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
D709 thru		
D711	19A700053P2	Silicon: 2 Diodes in Series; sim to BAV99.
D801	19A116585P1	Silicon, fast recovery, 600 mA, 50 PIV.
		IAOVO
1704		Port of printed wire board 10d003631D1
J701 J801	19A705482P1	Part of printed wire board 19d902631P1. Printed wire, 2-part; sim to SAMTEC SSW-112-01-
3301	10A100 <del>1</del> 02F1	SS.
J802	19B209648P1	Contact, electrical.
J901		Part of printed wire board.
		INDUCTORS
1.004	24442200047	
L301	344A3289P17	Fixed coil; 1 μH +5%. Sim to TDK NL252018T- 1ROJ.

SYMBOL	PART NO.	DESCRIPTION
		TRANSISTORS
Q601		
and Q602	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q603	19A700070F2	Silicon, PNP: sim to MMBT3906, low profile.
Q604	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q605	19A700026P2	Silicon, PNP: sim to BC369.
Q606	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.
Q607	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.
Q608	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q609	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q610	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile.
Q611	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q612 Q704	19A700059P2	Silicon, PNP: sim to MMBT3906, low profile. Silicon, NPN: sim to MMBT3904, low profile.
Q704 Q706	19A700076P2 19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
Q801	19A70007012	Silicon, PNP: sim to MMBT3906, low profile.
Q802		, · · · · · · · · · · · · · · · ·
thru		
Q804	19A700076P2	Silicon, NPN: sim to MMBT3904, low profile.
		RESISTORS
R301	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R302	19B801251P105	Metal film: 1M ohms ±5%, 1/10 w.
R303	19B801251P272	Metal film: 2.7K ohms ±5%, 1/10 w.
R304	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R305	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R306	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R307	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
R308	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R309 R310	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
and		
R311	19B801251P153	Metal film: 15K ohms ±5%, 1/10 w.
R312		
thru	4000040540404	
R314	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R315	19B801251P683	Metal film: 68K ohms ±5%, 1/10 w.
R316	19B801251P393	Metal film: 39K ohms ±5%, 1/10 w.
R317 R318	19B801251P563 19B801251P474	Metal film: 56K ohms ±5%, 1/10 w.
R319	19B801251P683	Metal film: 470K ohms ±5%, 1/10 w.
R320	19B801251P063	Metal film: 68K ohms $\pm$ 5%, 1/10 w. Metal film: 270K ohms $\pm$ 5%, 1/10 w.
R321	19A705496P7	· ·
R321	19B801251P183	Variable, surface mount: 100K ohms ±25%, 1/10 w. Metal film: 18K ohms ±5%, 1/10 w.
R324	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R325	19B801251P823	Metal film: 82K ohms ±5%, 1/10 w.
R326	19B801251P474	Metal film: 470K ohms ±5%, 1/10 w.
R327	19B801251P274	Metal film: 270K ohms ±5%, 1/10 w.
R328	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R329	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R330	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R601	19B801251P273	Metal film: 27K ohms ±5%, 1/10 w.
R602	19B801251P272	Metal film: 2.7K ohms ±5%, 1/10 w.
R603	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R604	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.
R605	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R606	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R607	19B801251P681	Metal film: 680 ohms ±5%, 1/10 w.
R608	19A705496P6	Resistor, variable surface mount: 50K ohms ±25%,
		adjustment range 15% to 85%; sim to MURATA Type RGV4E.
R609		
and R610	19B801251P153	Metal film: 15K ohms ±5%, 1/10 w.
R610 R611	19B801251P103	· ·
R612	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w. Metal film: 27K ohms ±5%, 1/10 w.
R612 R613	19B801251P273	Metal film: 27K onms ±5%, 1/10 w.  Metal film: 2.7K ohms ±5%, 1/10 w.
R614	19B801251P153	Metal film: 15K ohms ±5%, 1/10 w.
R615	19B801251P563	Metal film: 15K offins ±5%, 1/10 w.  Metal film: 56K ohms ±5%, 1/10 w.
R616	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R617	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
R618	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R619	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R620	19B801251P103	Metal film: 47K offins ±5%, 1/10 w.  Metal film: 10K ohms ±5%, 1/10 w.
R621	19B801251P562	Metal film: 5.6K ohms ±5%, 1/10 w.
R622	19B801251P222	Metal film: 2.2K ohms ±5%, 1/10 w.
R623	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R624	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R625	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R626	19B801251P471	Metal film: 470 ohms ±5%, 1/10 w.
R627	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.
R628	19B801251P823	Metal film: 82K ohms ±5%, 1/10 w.
R629	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R630	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.

SYMBOL	PART NO.	DESCRIPTION
Doo.	4000040540004	
R631	19B801251P824	Metal film: 820K ohms ±5%, 1/10 w.
R632	19B801251P154	Metal film: 150K ohms ±5%, 1/10 w.
R633	19B801251P821	Metal film: 820 ohms ±5%, 1/10 w.
R634	19B801251P272	Metal film: 2.7K ohms ±5%, 1/10 w.
R635	19B801251P822	Metal film: 8.2K ohms ±5%, 1/10 w.
R636	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R637	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R638	19B801251P823	Metal film: 82K ohms ±5%, 1/10 w.
R639	19B801251P154	Metal film: 150K ohms ±5%, 1/10 w.
R640	19B801251P274	Metal film: 270K ohms ±5%, 1/10 w.
R641	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R642	19B801251P102	Metal film: 1K ohms ±5%, 1/10 w.
R643	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R644	19B801251P123	Metal film: 12K ohms ±5%, 1/10 w.
R645	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R646		
thru R649	19B801251P100	Metal film: 10 ohms ±5%, 1/10 w.
R650	19B801251P154	Metal film: 150K ohms ±5%, 1/10 w.
R651	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R652		
and		
R653	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R654	19B801251P682	Metal film: 6.8K ohms ±5%, 1/10 w.
R655		
and R656	19B801251P474	Metal film: 470K ohms ±5%, 1/10 w.
R657	19B801251P473	Metal film: 470k offins ±5%, 1/10 w.
R658	19B801251P333	Metal film: 47K offins ±5%, 1/10 w.  Metal film: 33K ohms ±5%, 1/10 w.
R659	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R660	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R661	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R662		Wotal IIIII. 1001COIIII0 ±070, 1710 W.
and		
R663	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R664	19A705813P1	Thermistor: sim to AL03006-624-73-G100.
R665	19B801251P124	Metal film: 120K ohms ±5%, 1/10 w.
R666	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R667	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R668 and		
R669	19B801251P333	Metal film: 33K ohms ±5%, 1/10 w.
R670	19B801251P563	Metal film: 56K ohms ±5%, 1/10 w.
R671	19B801251P222	Metal film: 2.2K ohms ±5%, 1/10 w.
R672	19B801251P561	Metal film: 560 ohms ±5%, 1/10 w.
R673	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R674	19B801251P684	Metal film: 680K ohms ±5%, 1/10 w.
R675	19B801251P474	Metal film: 470K ohms ±5%, 1/10 w.
R676	19B801251P394	Metal film: 390K ohms ±5%, 1/10 w.
R677	19B801251P334	Metal film: 330K ohms ±5%, 1/10 w.
R678	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R679	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R701 thru		
R704	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R705	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R706	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R712	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R715		
thru	400004654545	
R719	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R720	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R721	19B801251P103	Metal film: 10K ohms ±5%, 1/10 w.
R722	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R723 thru		
R725	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R726	19B801251P824	Metal film: 820K ohms ±5%, 1/10 w.
R727	19B801251P394	Metal film: 390K ohms ±5%, 1/10 w.
R728	19B801251P224	Metal film: 220K ohms ±5%, 1/10 w.
R729	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R730	19A702931P234	Metal film: 2210 ohms ±1%, 200 VDCW, 1/8 w.
R731	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R732	19B801251P333	Metal film: 33K ohms $\pm$ 5%, 1/10 w.
R733	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R734		
thru R736	19B801251P104	Metal film: 100K ohms ±5%, 1/10 w.
R737	19B801251P473	Metal film: 47K ohms ±5%, 1/10 w.
R738	19B801251P104	Metal film: 47K offins ±5%, 1/10 w.
R739	19B801251P472	Metal film: 4.7K ohms ±5%, 1/10 w.
R801	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.
R802	19B801251P183	Metal film: 18K ohms ±5%, 1/10 w.
R803	19B801251P222	Metal film: 2.2K ohms ±5%, 1/10 w.
R804		,
and	4000040540000	Matal films 001/ along 150/ 1/10
R805	19B801251P223	Metal film: 22K ohms ±5%, 1/10 w.

LBI-38975 PARTS LIST

SYMBOL	PART NO.	DESCRIPTION
R806 R807 R808 R809 R810	19B801251P473 19B801251P472 19B801251P104 19B801251P333 19B801251P473	Metal film: 47K ohms ±5%, 1/10 w. Metal film: 4.7K ohms ±5%, 1/10 w. Metal film: 100K ohms ±5%, 1/10 w. Metal film: 33K ohms ±5%, 1/10 w. Metal film: 47K ohms ±5%, 1/10 w.
U301 U302	19A705450P2	INTEGRATED CIRCUITS Dual Operational Amplifier, sim to MC34072.
and U303 U601 U602 U603	19A702293P3 19A702293P1 19A702293P3 19A702705P3	Linear: Dual Op Amp; sim to LM358D. Linear: Quad Op Amp; sim to LM324D. Linear: Dual Op Amp; sim to LM358D. Digital: 8-Channel Analog Multiplexer; sim to
U604 U605	19A705452P1 19A702705P4	4051BM. Linear: Audio Amplifier; sim to TDA 2822M. Digital: Quad Analog Switch/Multiplexer; sim to 4066BM.
U606 U701 U801 U802 U803 U804	19A702293P3 19A704724P205 19A705454P1 19A702536P1 19A703987P322 RYT1186063/1	Linear: Dual Op Amp; sim to LM358D. EEPROM: CMOS, sim to Seiko S8054ALO. Voltage Detector, sim to Seiko S 8054ALO. Sinear positive voltage regulator; sim to LM2931AZ- 8-bit shift register. Digital: 48-Bit Serial Number ROM.
Y701	19A702511G26	
	19A702364P310 19B801570P2 19A705662P1	Machine screw, TORX Drive: No. M3-0.5 x 10. Connector holder. Connector, Elastomeric.
A3		FRONT CAP ASSEMBLY (CONVENTIONAL) 19D902180G10 (CONVENTIONAL/DTMF) 19D902180G11
B902	19A149673P1	Round: Water Proof, 24 ohms, 1/2 w.; sim to Line Electric Co. VS-50W24.
	19A702364P1305 19C851997P1 19C851636P2 19A705777P1	MISCELLANEOUS Machine screw. Gasket, Speaker. Switch pad. Nameplate.
	19A116318P4 19A705664P1 344A4654P1 19B801566P8	FRONT COVER ASSEMBLY (CONVENTIONAL) 19D902072G17 Foil, Magnetic shielding: 1.5 inches long Gasket Gasket Shield
		FRONT COVER ASSEMBLY (CONVENTIONAL) 19D902072G18
	19D902072P4 19D902072P13 19A116318P4 19A705664P1 19A705651P1 19A702364P304 19A705861P1 19C851992G1	Keypad, DTMF Cable, SCAN/DTMF Foil, Magnetic shielding: 1.5 inches long. Gasket. Loudspeaker, permanent magnet. Machine screw. Diaphragm. Board, SCAN/DTMF.
		LCD ASSEMBLY 19A705090G6
H1	19C851660P2	Display crystal.

SYMBOL	PART NO.	DESCRIPTION
STIVIBUL	PARTINU.	DESCRIPTION
	19A703685P3 19B801569P1 19C851719P2	MISCELLANEOUS LCD connector. Diffuser. Lens.
		CONTROL ASSEMBLY 19A705090G10
C3		CAPACITORS
thru C7	19A702052P3	Ceramic: 470 pF ±10%, 50 VDCW.
J1	19A115834P1	Contact, electrical: sim to AMP 2-330808-8.
M1	19A701301P3	Cartridge: Electret.
S1 S2	19A705712P1 19A705712P2	Subminiature switch. Subminiature switch.
29 32 36	19A705733P4 19B801571P2 19C851722P1	MISCELLANEOUS Contact frame, circuitized. Dome switch. Auxiliary boot jack.
		CONVENTIONAL/DTMF BOARD 19C851992G1
C1 C2 C3 C4 C5 C6 C7	19A705205P206 19A705205P223 19A702052P6 19A702052P14 19A702052P3 19A702052P14 19A702052P5	Tantalum: 10.0 μF ±20%, 16 VDCW.  Tantalum: 22 μF, 6 VDCW; sim to Sprague 293D.  Ceramic: 1500 pF ±10%, 50 VDCW.  Ceramic: 0.01 μF ±10%, 50 VDCW.  Ceramic: 470 pF ±10%, 50 VDCW.  Ceramic: 0.01 μF ±10%, 50 VDCW.  Ceramic: 1000 pF ±10%, 50 VDCW.
D1	19A702526P2	Silicon: Schottky Barrier; sim to BAT 17.
J802		Part of printed wire board.
Q1	19A134739P2	TRANSISTORSSilicon, NPN.
Q2 and Q3 Q4	19A700076P2 19A700059P2	Silicon, NPN: sim to MMBT3904, low profile. Silicon, PNP: sim to MMBT3906, low profile.
R2 R3 R4 R5 thru R8 R9 R10 R11 R12 R13 R14 R15 and R16 R17	19A149818P473 19A149818P104 19A149818P822 19A149818P23 19A149818P23 19A149818P154 19A149818P153 19A149818P23 19A149818P23 19A149818P23	RESISTORS
R18 R19 R20 R21 R22 R23	19A149818P224 19A149818P103 19A149818P392 19A149818P103 19A149818P273 19A149818P562	Metal film: 220K ohms ±5%, 1/16 w.  Metal film: 10K ohms ±5%, 1/16 w.  Metal film: 3.9K ohms ±5%, 1/16 w.  Metal film: 10K ohms ±5%, 1/16 w.  Metal film: 27K ohms ±5%, 1/16 w.  Metal film: 5.6K ohms ±5%, 1/16 w.

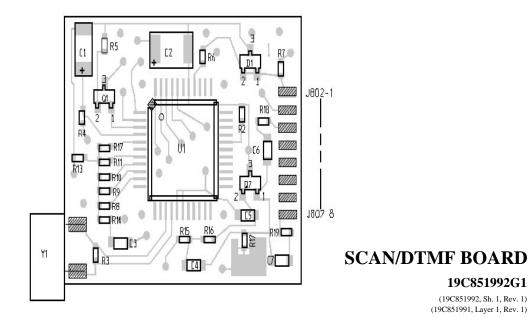
SYMBOL	PART NO.	DESCRIPTION
		INTEGRATED CIRCUITS
U1	19A704345P30	Integrated circuit, Digital CHMOS: 8-bit micro procssor.
		CRYSTALS
Y1	19A702511G26	Quartz: 11.0592 MHz.
		LCD DRIVER BOARD 19C851720G1
		CAPACITORS
C1 C2	19A702052P6 19A702052P26	Ceramic: 1500 pF $\pm$ 10%, 50 VDCW. Ceramic: 0.1 $\mu$ F $\pm$ 10%, 50 VDCW
		DIODES
D1 thru D4	19A705713P1	LED, Subminiature.
		JACKS
J2		Part of printed wire board.
		PLUGS
P1 P2	19B801235P13 19B801235P3	Electrical contact. Electrical contact.
		TRANSISTORS
Q1 Q2	19A700059P2 19A700076P2	Silicon, PNP: sim to MMBT3906, low profile. Silicon, NPN: sim to MMBT3904, low profile.
		RESISTORS
R1 R2 R3	19B801251P105 19B801251P221	Metal film: 1M ohms $\pm 5\%$ , 1/10 w. Metal film: 220 ohms $\pm 5\%$ , 1/10 w.
and R4 R5	19B801251P124	Metal film: 120K ohms ±5%, 1/10 w.
and R6 R7	19B801251P472 19B801251P221	Metal film: 4.7K ohms ±5%, 1/10 w. Metal film: 220 ohms ±5%, 1/10 w.
		INTEGRATED CIRCUITS
U1	19A705714P1	LCD driver chip.
		MISCELLANEOUS
4	19C851720G7	LCD driver.

OUTLINE DIAGRAM LBI-38975

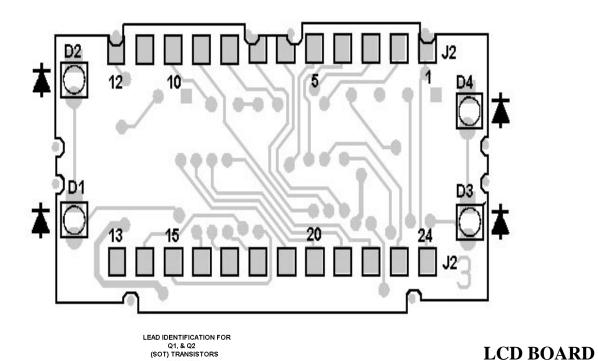
#### **COMPONENT SIDE**

## 

#### **COMPONENT SIDE**



#### **SOLDER SIDE**



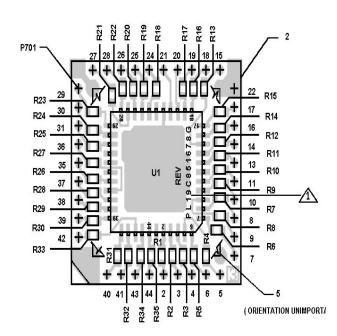
(B) 2 3 (C)

19C851720G1

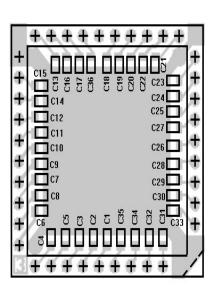
(19C851720, Sh. 1, Rev. 3)

(19C851721, Component Side, Rev. 3) (19C851721, Solder Side, Rev. 3)

#### **COMPONENT SIDE**



#### **SOLDER SIDE**



#### **SPUR FILTER BOARD**

#### 19C851678G4

(19C851678, Rev. 1) (19C851679, Comp. Side, Rev. 3) (19C851679, Solder Side, Rev. 3) LBI-38975 **OUTLINE DIAGRAM** 

### **COMPONENT SIDE**









0290

27+28+26+25+24+21+20+19+18+15+ C609 13

C317\_\_\_

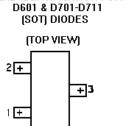
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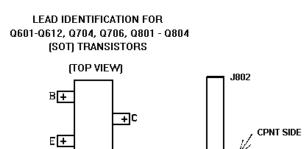
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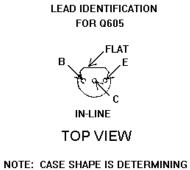
A701 - J01 J901 <

10601 REDI

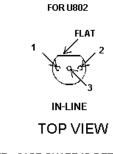
LEAD IDENTIFICATION FOR D601 & D701-D711 (SOT) DIODES (TOP VIEW) 2 +







FACTOR FOR LEAD IDENTIFICATION.



LEAD IDENTIFICATION

**SOLDER SIDE** 

C804

C907

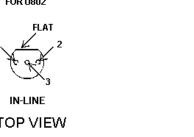
П П 0703

П П 07Ø1

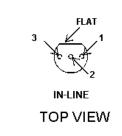
87Ø2

R809 R808

U



Q6Ø1



LEAD IDENTIFICATION

FOR U801

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

NOTE: CASE SHAPE IS DETERMINING FACTOR FOR LEAD IDENTIFICATION.

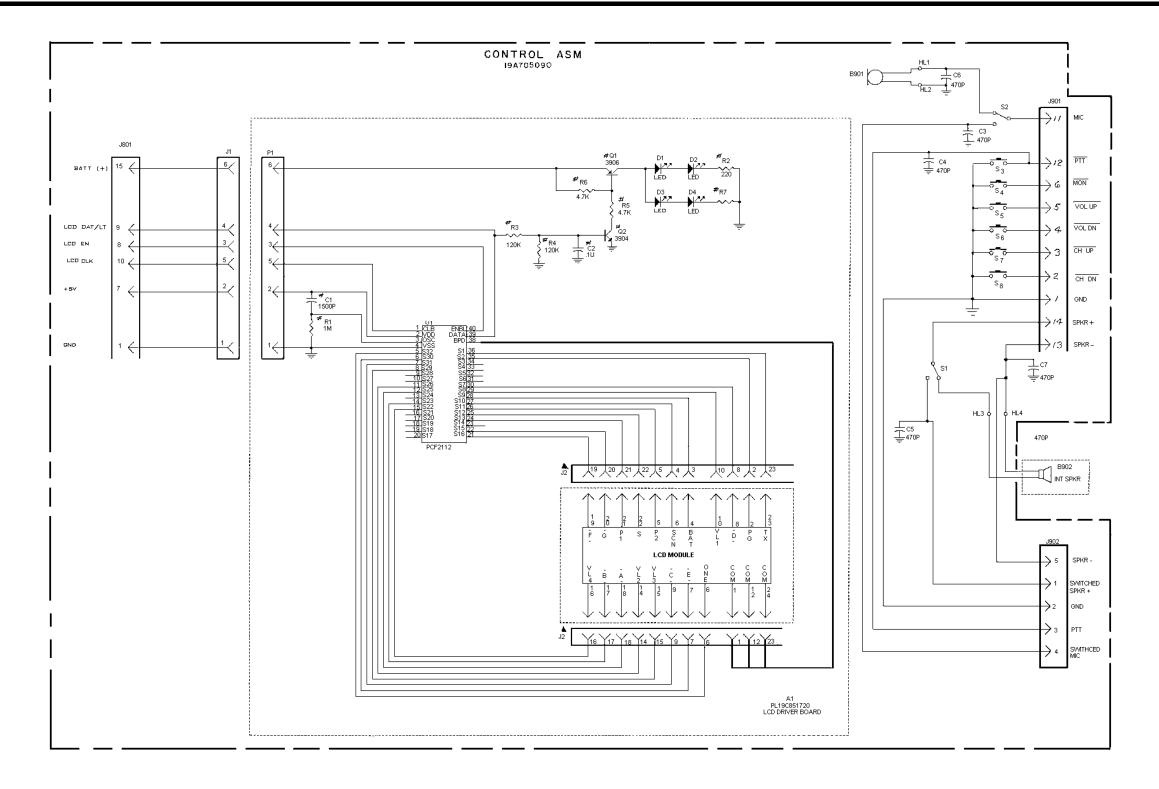
#### **AUDIO/LOGIC BOARD**

#### 19D902631G2

(19D902631, Rev. 2) (19D902632, Layer 1, Rev. 1) (19D902632, Layer 4, Rev. 1)

#### 16

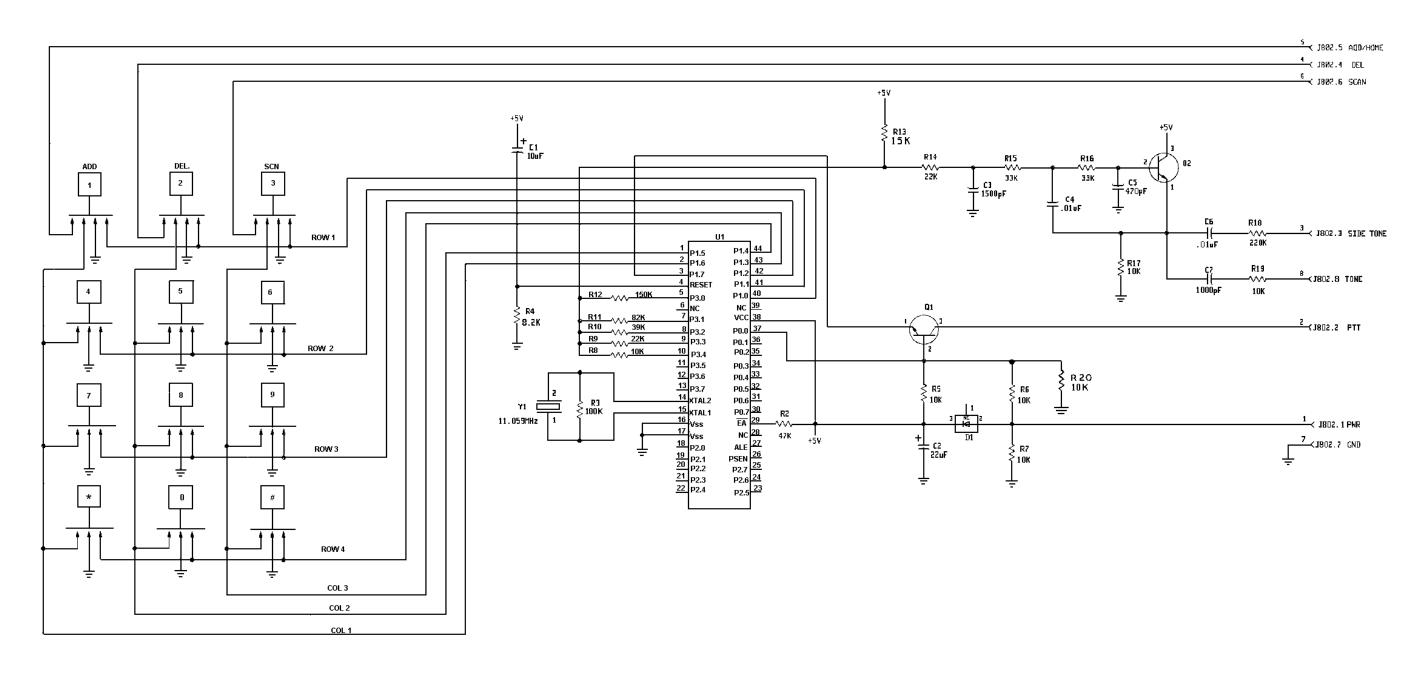
SCHEMATIC DIAGRAM LBI-38975



#### FRONT CAP ASSEMBLY

#### 19D902180G10 & G11

(19D902216, SH. 2, REV. 3)

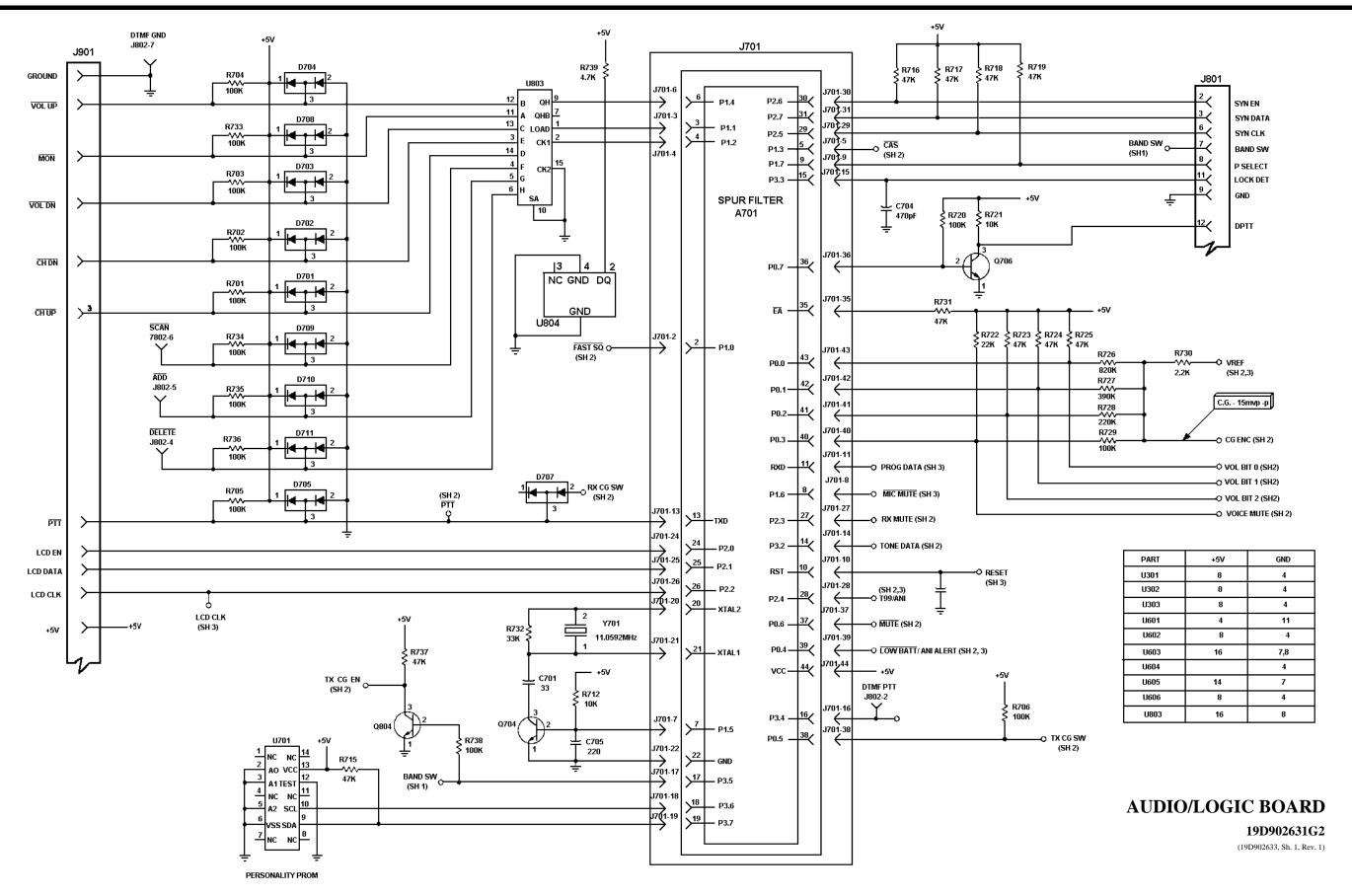


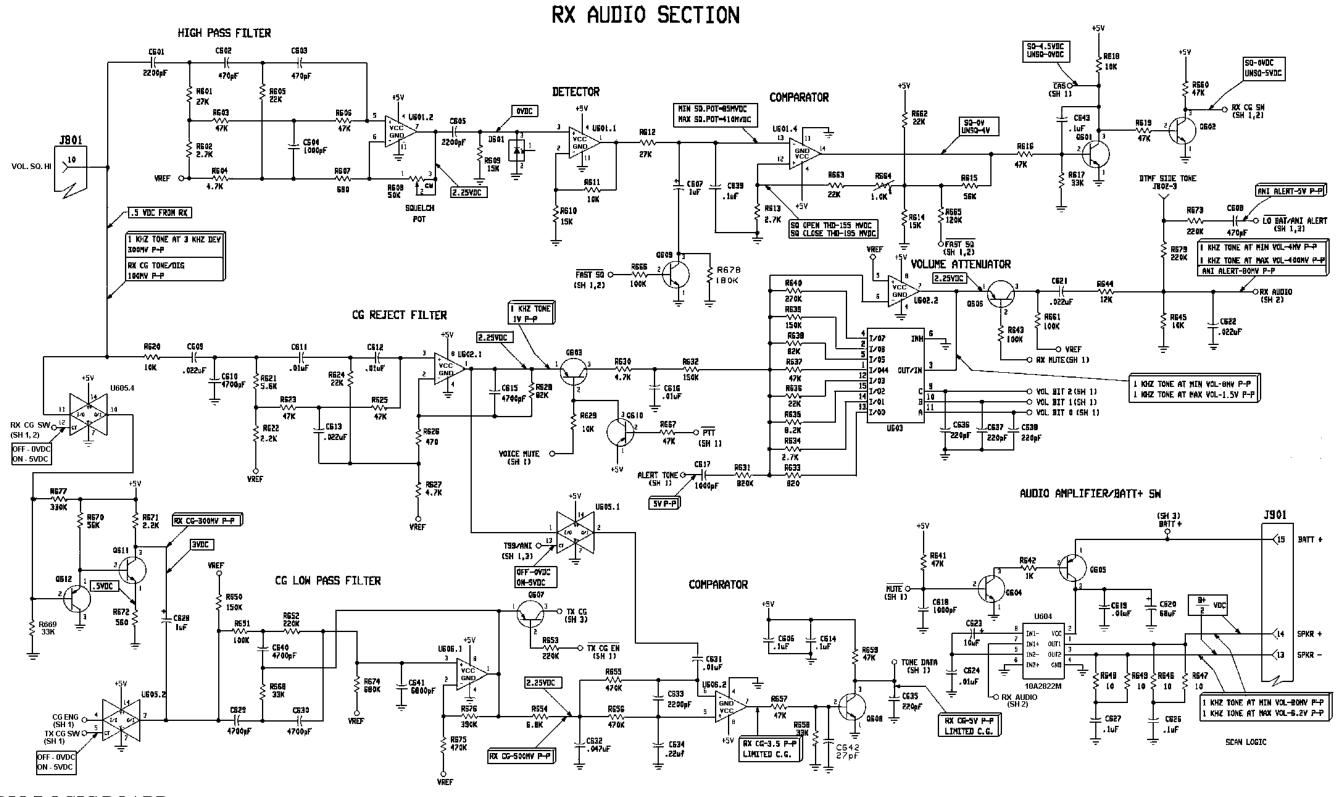
#### SCAN/DTMF BOARD

19C851992G1

(19D902999, Sh. 1, Rev. 2)

SCHEMATIC DIAGRAM LBI-38975





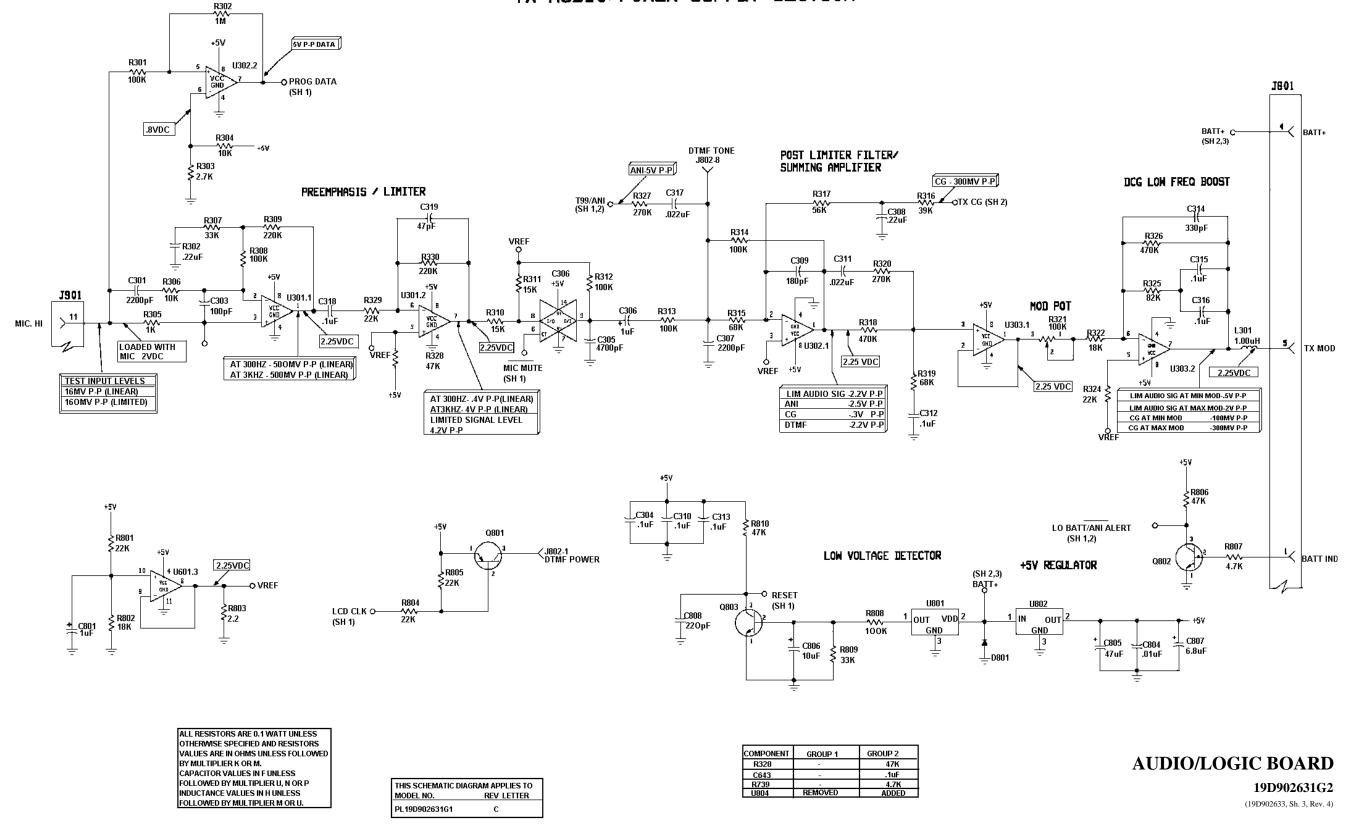
#### **AUDIO/LOGIC BOARD**

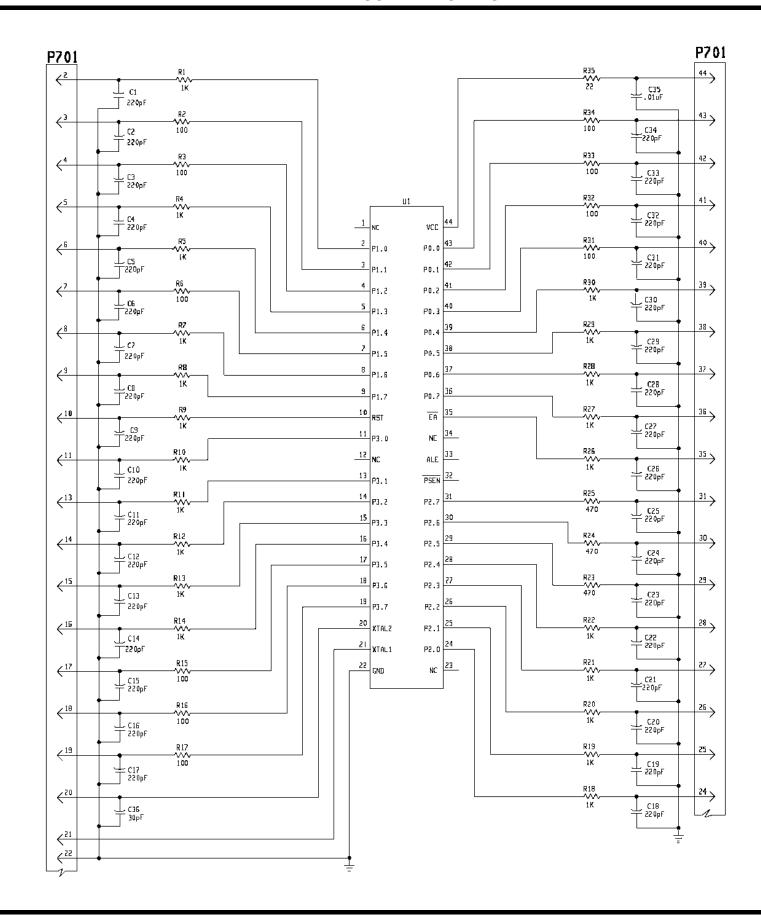
19D902631G2

(19D902633, Sh. 2, Rev. 2)

SCHEMATIC DIAGRAM LBI-38975

#### TX AUDIO/POWER SUPPLY SECTION





ALL RESISTORS ARE 0.1 HATT UNLESS OTHERHISE SPECIFIED AND RESISTORS VALUES ARE IN OHMS UNLESS FOLLOMED BY MULTIPLIER K OR M. CAPACITOR VALUES IN F UNLESS FOLLOMED BY MULTIPLIER U, N OR P INDUCTANCE VALUES IN H UNLESS FOLLOMED BY MULTIPLIER H OR U

THIS SCHEMATIC DIAGRAM APPLIES TO				
HODEL NO.	REV LETTER			
190851678G1	c			
19C85167BG2	С			
19C851678G3	В			

#### **SPUR FILTER BOARD**

19C851678G4

(19D902215, Rev. 6)

LBI-38975

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